



June 2006
UniFET™

FDP75N08

75V N-Channel MOSFET

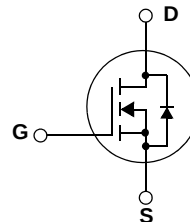
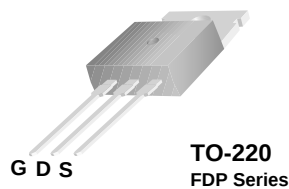
Features

- 75A, 75V, $R_{DS(on)} = 0.011\Omega$ @ $V_{GS} = 10V$
- Low gate charge (typical 150 nC)
- Low C_{rss} (typical 85 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies, active power factor correction, electronic lamp ballast based on half bridge topology.



Absolute Maximum Ratings

Symbol	Parameter	FDP75N08	Units
V_{DSS}	Drain-Source Voltage	75	V
I_D	Drain Current - Continuous ($T_C = 25^\circ C$)	75	A
	- Continuous ($T_C = 100^\circ C$)	47.7	A
I_{DM}	Drain Current - Pulsed (Note 1)	300	A
V_{GSS}	Gate-Source Voltage	± 20	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	1164	mJ
I_{AR}	Avalanche Current (Note 1)	75	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	13.1	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.5	V/ns
P_D	Power Dissipation ($T_C = 25^\circ C$)	131	W
	- Derate above $25^\circ C$	1	W/ $^\circ C$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ C$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ C$

Thermal Characteristics

Symbol	Parameter	FDP75N08	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.95	$^\circ C/W$
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	$^\circ C/W$

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP75N08	FDP75N08	TO-220	--	--	50

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	75	--	--	V
ΔBV _{DSS} /ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	--	0.6	--	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 75 V, V _{GS} = 0 V	--	--	1	μA
		V _{DS} = 60 V, T _C = 125°C	--	--	10	μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 20 V, V _{DS} = 0 V	--	--	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -20 V, V _{DS} = 0 V	--	--	-100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	2.0	--	4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 37.5 A	--	9.5	11	mΩ
g _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D =37.5 A (Note 4)	--	15	--	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz	--	2940	3820	pF
C _{oss}	Output Capacitance		--	680	890	pF
C _{rss}	Reverse Transfer Capacitance		--	85	125	pF
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 37.5 V, I _D = 75A, R _G = 25 Ω (Note 4, 5)	--	7.2	25	ns
t _r	Turn-On Rise Time		--	68	146	ns
t _{d(off)}	Turn-Off Delay Time		--	77	164	ns
t _f	Turn-Off Fall Time		--	93	196	ns
Q _g	Total Gate Charge	V _{DS} = 60 V, I _D = 75A, V _{GS} = 10 V (Note 4, 5)	--	64	84	nC
Q _{gs}	Gate-Source Charge		--	16	--	nC
Q _{gd}	Gate-Drain Charge		--	24	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	75	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	300	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 75 A	--	--	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 75 A, dI _F / dt = 100 A/μs (Note 4)	--	62	--	ns
Q _{rr}	Reverse Recovery Charge		--	150	--	nC

NOTES:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 138\text{ }\mu\text{H}$, $I_{AS} = 75\text{ A}$, $V_{DD} = 50\text{ V}$, $R_G = 25\text{ }\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 75\text{ A}$, $di/dt \leq 200\text{ A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width $\leq 300\text{ }\mu\text{s}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature

Typical Performance Characteristics

Figure 1. On-Region Characteristics

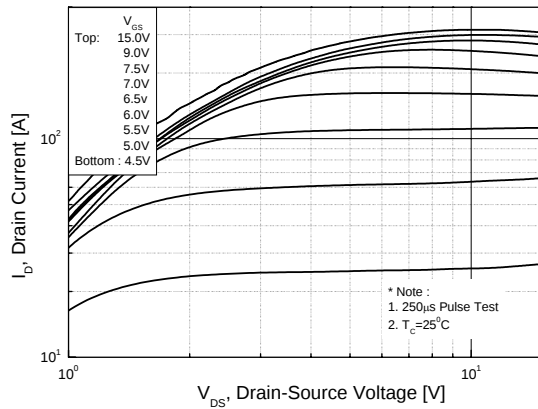


Figure 2. Transfer Characteristics

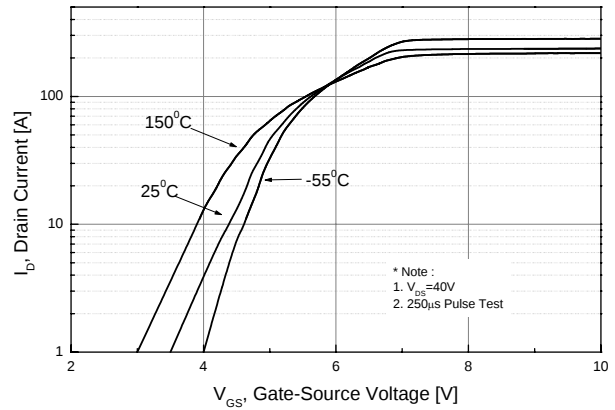


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

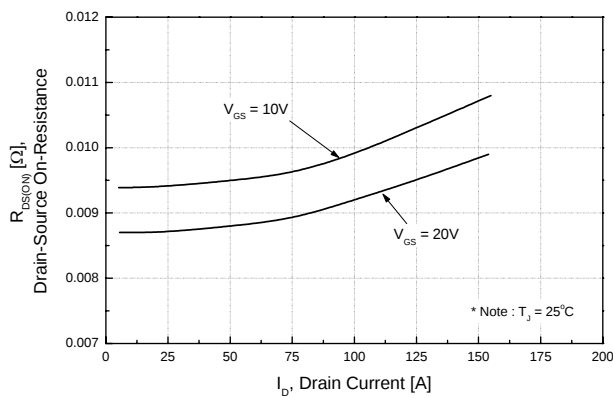


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

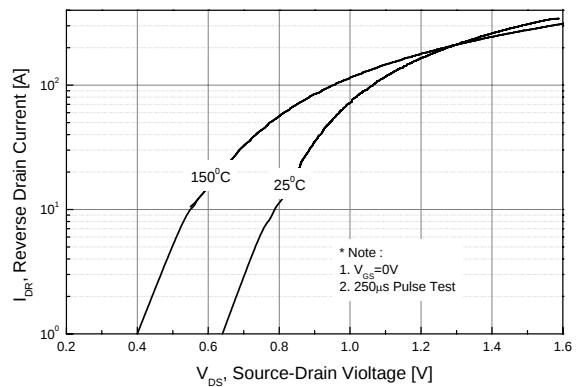


Figure 5. Capacitance Characteristics

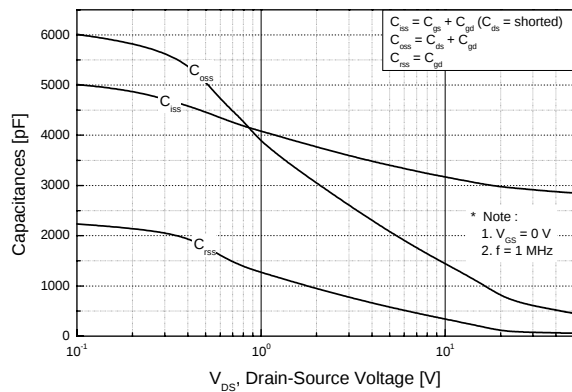
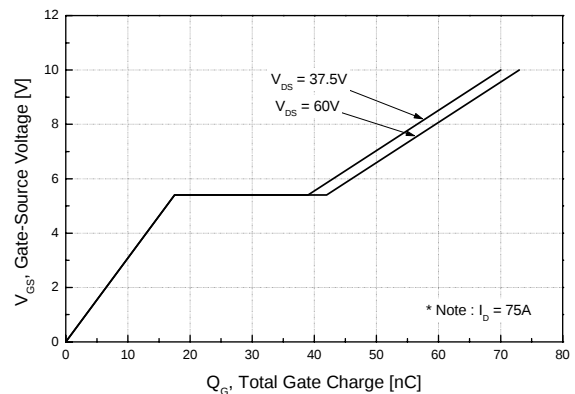


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

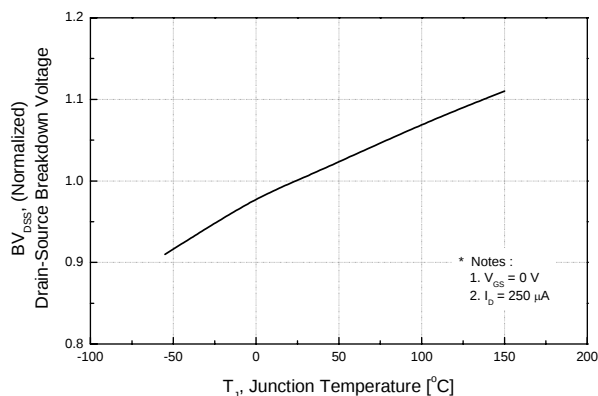


Figure 8. On-Resistance Variation vs. Temperature

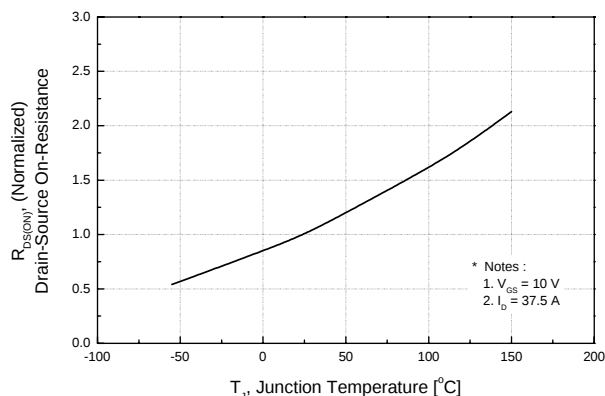


Figure 9. Maximum Safe Operating Area

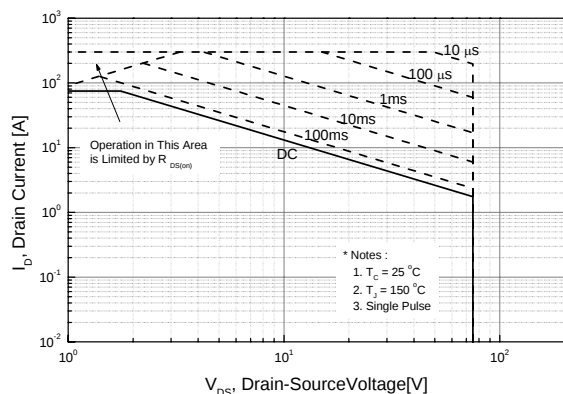


Figure 10. Maximum Drain Current vs. Case Temperature

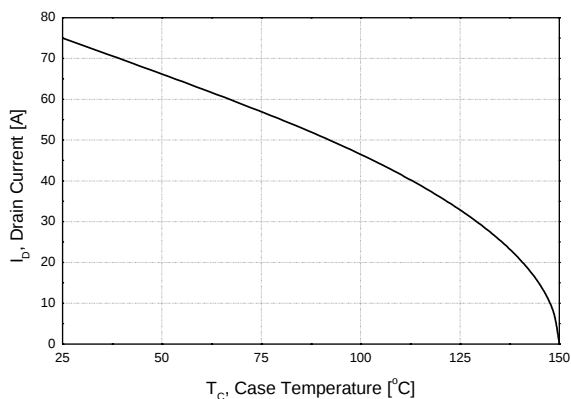
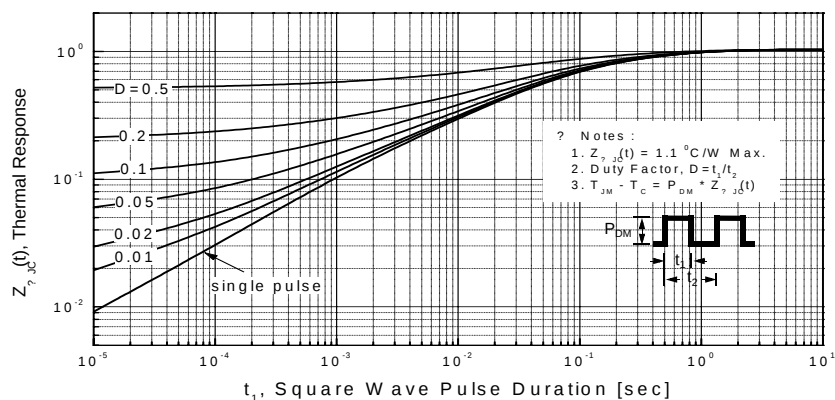
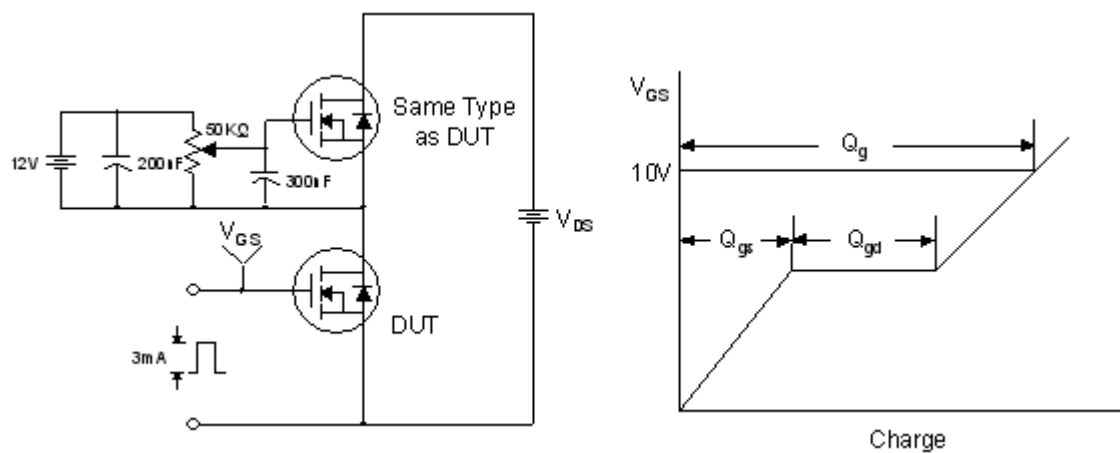


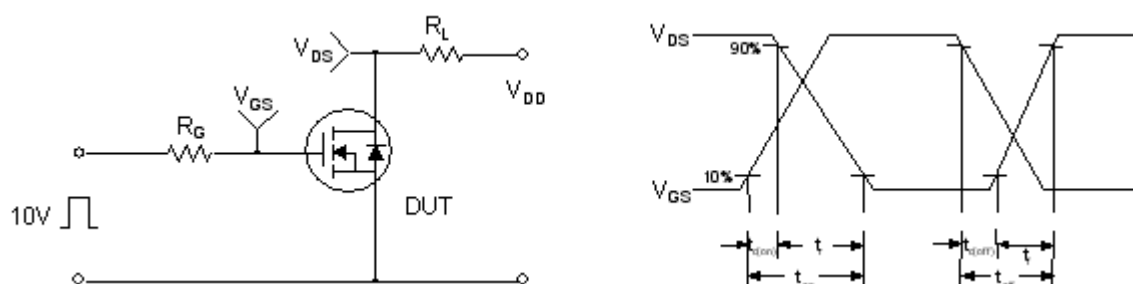
Figure 11. Transient Thermal Response Curve



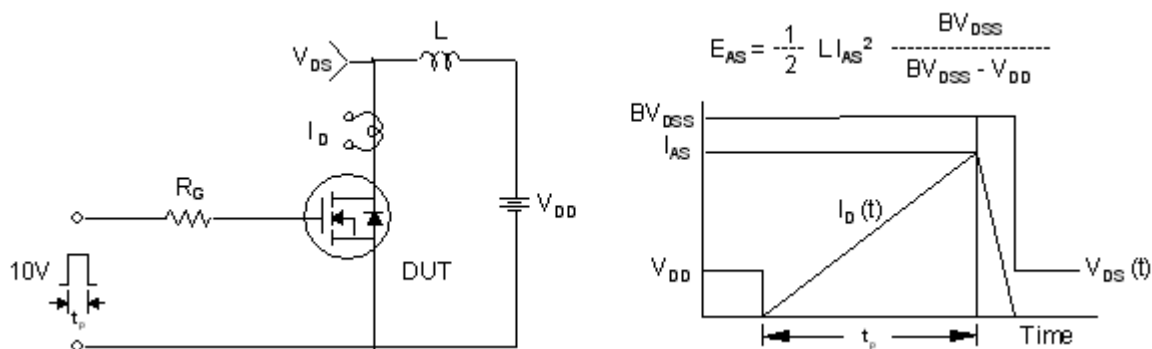
Gate Charge Test Circuit & Waveform

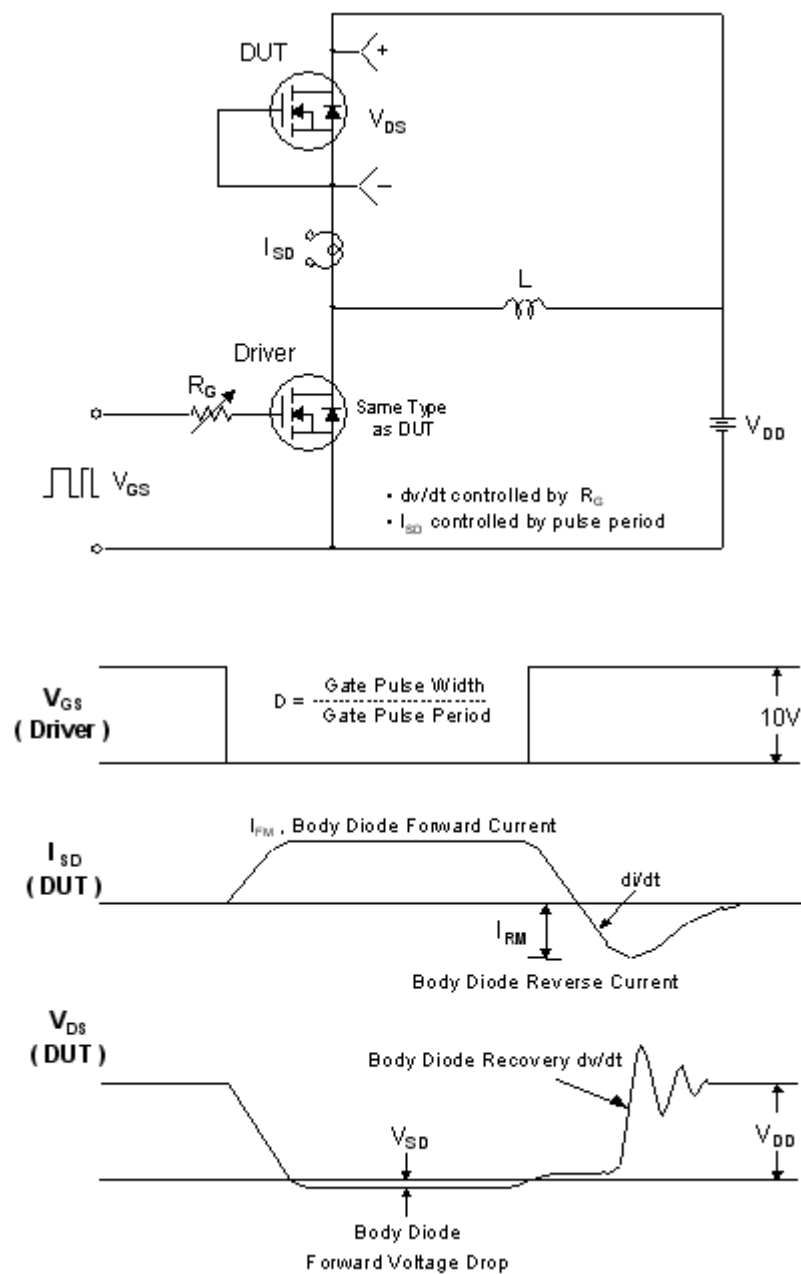


Resistive Switching Test Circuit & Waveforms



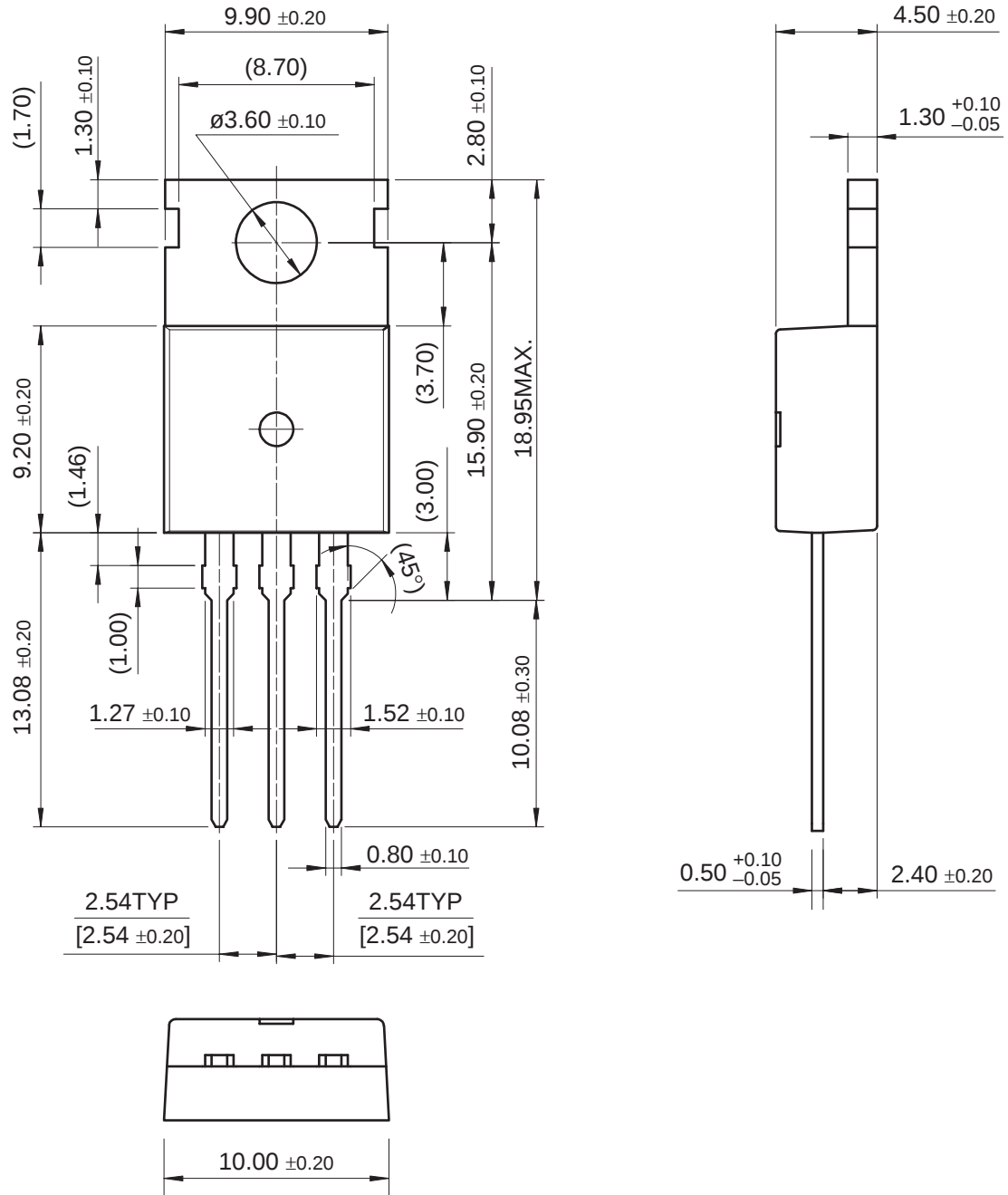
Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions

TO-220



Dimensions in Millimeters

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